

To our customers,

Old Company Name in Catalogs and Other Documents

On April 1st, 2010, NEC Electronics Corporation merged with Renesas Technology Corporation, and Renesas Electronics Corporation took over all the business of both companies. Therefore, although the old company name remains in this document, it is a valid Renesas Electronics document. We appreciate your understanding.

Renesas Electronics website: <http://www.renesas.com>

April 1st, 2010
Renesas Electronics Corporation

Issued by: Renesas Electronics Corporation (<http://www.renesas.com>)

Send any inquiries to <http://www.renesas.com/inquiry>.

Notice

1. All information included in this document is current as of the date this document is issued. Such information, however, is subject to change without any prior notice. Before purchasing or using any Renesas Electronics products listed herein, please confirm the latest product information with a Renesas Electronics sales office. Also, please pay regular and careful attention to additional and different information to be disclosed by Renesas Electronics such as that disclosed through our website.
2. Renesas Electronics does not assume any liability for infringement of patents, copyrights, or other intellectual property rights of third parties by or arising from the use of Renesas Electronics products or technical information described in this document. No license, express, implied or otherwise, is granted hereby under any patents, copyrights or other intellectual property rights of Renesas Electronics or others.
3. You should not alter, modify, copy, or otherwise misappropriate any Renesas Electronics product, whether in whole or in part.
4. Descriptions of circuits, software and other related information in this document are provided only to illustrate the operation of semiconductor products and application examples. You are fully responsible for the incorporation of these circuits, software, and information in the design of your equipment. Renesas Electronics assumes no responsibility for any losses incurred by you or third parties arising from the use of these circuits, software, or information.
5. When exporting the products or technology described in this document, you should comply with the applicable export control laws and regulations and follow the procedures required by such laws and regulations. You should not use Renesas Electronics products or the technology described in this document for any purpose relating to military applications or use by the military, including but not limited to the development of weapons of mass destruction. Renesas Electronics products and technology may not be used for or incorporated into any products or systems whose manufacture, use, or sale is prohibited under any applicable domestic or foreign laws or regulations.
6. Renesas Electronics has used reasonable care in preparing the information included in this document, but Renesas Electronics does not warrant that such information is error free. Renesas Electronics assumes no liability whatsoever for any damages incurred by you resulting from errors in or omissions from the information included herein.
7. Renesas Electronics products are classified according to the following three quality grades: "Standard", "High Quality", and "Specific". The recommended applications for each Renesas Electronics product depends on the product's quality grade, as indicated below. You must check the quality grade of each Renesas Electronics product before using it in a particular application. You may not use any Renesas Electronics product for any application categorized as "Specific" without the prior written consent of Renesas Electronics. Further, you may not use any Renesas Electronics product for any application for which it is not intended without the prior written consent of Renesas Electronics. Renesas Electronics shall not be in any way liable for any damages or losses incurred by you or third parties arising from the use of any Renesas Electronics product for an application categorized as "Specific" or for which the product is not intended where you have failed to obtain the prior written consent of Renesas Electronics. The quality grade of each Renesas Electronics product is "Standard" unless otherwise expressly specified in a Renesas Electronics data sheets or data books, etc.

"Standard": Computers; office equipment; communications equipment; test and measurement equipment; audio and visual equipment; home electronic appliances; machine tools; personal electronic equipment; and industrial robots.

"High Quality": Transportation equipment (automobiles, trains, ships, etc.); traffic control systems; anti-disaster systems; anti-crime systems; safety equipment; and medical equipment not specifically designed for life support.

"Specific": Aircraft; aerospace equipment; submersible repeaters; nuclear reactor control systems; medical equipment or systems for life support (e.g. artificial life support devices or systems), surgical implantations, or healthcare intervention (e.g. excision, etc.), and any other applications or purposes that pose a direct threat to human life.

8. You should use the Renesas Electronics products described in this document within the range specified by Renesas Electronics, especially with respect to the maximum rating, operating supply voltage range, movement power voltage range, heat radiation characteristics, installation and other product characteristics. Renesas Electronics shall have no liability for malfunctions or damages arising out of the use of Renesas Electronics products beyond such specified ranges.
9. Although Renesas Electronics endeavors to improve the quality and reliability of its products, semiconductor products have specific characteristics such as the occurrence of failure at a certain rate and malfunctions under certain use conditions. Further, Renesas Electronics products are not subject to radiation resistance design. Please be sure to implement safety measures to guard them against the possibility of physical injury, and injury or damage caused by fire in the event of the failure of a Renesas Electronics product, such as safety design for hardware and software including but not limited to redundancy, fire control and malfunction prevention, appropriate treatment for aging degradation or any other appropriate measures. Because the evaluation of microcomputer software alone is very difficult, please evaluate the safety of the final products or system manufactured by you.
10. Please contact a Renesas Electronics sales office for details as to environmental matters such as the environmental compatibility of each Renesas Electronics product. Please use Renesas Electronics products in compliance with all applicable laws and regulations that regulate the inclusion or use of controlled substances, including without limitation, the EU RoHS Directive. Renesas Electronics assumes no liability for damages or losses occurring as a result of your noncompliance with applicable laws and regulations.
11. This document may not be reproduced or duplicated, in any form, in whole or in part, without prior written consent of Renesas Electronics.
12. Please contact a Renesas Electronics sales office if you have any questions regarding the information contained in this document or Renesas Electronics products, or if you have any other inquiries.

(Note 1) "Renesas Electronics" as used in this document means Renesas Electronics Corporation and also includes its majority-owned subsidiaries.

(Note 2) "Renesas Electronics product(s)" means any product developed or manufactured by or for Renesas Electronics.

To all our customers

Regarding the change of names mentioned in the document, such as Hitachi Electric and Hitachi XX, to Renesas Technology Corp.

The semiconductor operations of Mitsubishi Electric and Hitachi were transferred to Renesas Technology Corporation on April 1st 2003. These operations include microcomputer, logic, analog and discrete devices, and memory chips other than DRAMs (flash memory, SRAMs etc.) Accordingly, although Hitachi, Hitachi, Ltd., Hitachi Semiconductors, and other Hitachi brand names are mentioned in the document, these names have in fact all been changed to Renesas Technology Corp. Thank you for your understanding. Except for our corporate trademark, logo and corporate statement, no changes whatsoever have been made to the contents of the document, and these changes do not constitute any alteration to the contents of the document itself.

Renesas Technology Home Page: <http://www.renesas.com>

Renesas Technology Corp.
Customer Support Dept.
April 1, 2003

Cautions

Keep safety first in your circuit designs!

1. Renesas Technology Corporation puts the maximum effort into making semiconductor products better and more reliable, but there is always the possibility that trouble may occur with them. Trouble with semiconductors may lead to personal injury, fire or property damage.
Remember to give due consideration to safety when making your circuit designs, with appropriate measures such as (i) placement of substitutive, auxiliary circuits, (ii) use of nonflammable material or (iii) prevention against any malfunction or mishap.

Notes regarding these materials

1. These materials are intended as a reference to assist our customers in the selection of the Renesas Technology Corporation product best suited to the customer's application; they do not convey any license under any intellectual property rights, or any other rights, belonging to Renesas Technology Corporation or a third party.
2. Renesas Technology Corporation assumes no responsibility for any damage, or infringement of any third-party's rights, originating in the use of any product data, diagrams, charts, programs, algorithms, or circuit application examples contained in these materials.
3. All information contained in these materials, including product data, diagrams, charts, programs and algorithms represents information on products at the time of publication of these materials, and are subject to change by Renesas Technology Corporation without notice due to product improvements or other reasons. It is therefore recommended that customers contact Renesas Technology Corporation or an authorized Renesas Technology Corporation product distributor for the latest product information before purchasing a product listed herein.
The information described here may contain technical inaccuracies or typographical errors.
Renesas Technology Corporation assumes no responsibility for any damage, liability, or other loss rising from these inaccuracies or errors.
Please also pay attention to information published by Renesas Technology Corporation by various means, including the Renesas Technology Corporation Semiconductor home page (<http://www.renesas.com>).
4. When using any or all of the information contained in these materials, including product data, diagrams, charts, programs, and algorithms, please be sure to evaluate all information as a total system before making a final decision on the applicability of the information and products. Renesas Technology Corporation assumes no responsibility for any damage, liability or other loss resulting from the information contained herein.
5. Renesas Technology Corporation semiconductors are not designed or manufactured for use in a device or system that is used under circumstances in which human life is potentially at stake. Please contact Renesas Technology Corporation or an authorized Renesas Technology Corporation product distributor when considering the use of a product contained herein for any specific purposes, such as apparatus or systems for transportation, vehicular, medical, aerospace, nuclear, or undersea repeater use.
6. The prior written approval of Renesas Technology Corporation is necessary to reprint or reproduce in whole or in part these materials.
7. If these products or technologies are subject to the Japanese export control restrictions, they must be exported under a license from the Japanese government and cannot be imported into a country other than the approved destination.
Any diversion or reexport contrary to the export control laws and regulations of Japan and/or the country of destination is prohibited.
8. Please contact Renesas Technology Corporation for further details on these materials or the products contained therein.

**E6000 SIMM Memory Module
for SH7010, SH7040, SH7050
(HS6000EMS21H/HS6000EMS22H)
User's Manual**

Cautions

1. Hitachi neither warrants nor grants licenses of any rights of Hitachi's or any third party's patent, copyright, trademark, or other intellectual property rights for information contained in this document. Hitachi bears no responsibility for problems that may arise with third party's rights, including intellectual property rights, in connection with use of the information contained in this document.
2. Products and product specifications may be subject to change without notice. Confirm that you have received the latest product standards or specifications before final design, purchase or use.
3. Hitachi makes every attempt to ensure that its products are of high quality and reliability. However, contact Hitachi's sales office before using the product in an application that demands especially high quality and reliability or where its failure or malfunction may directly threaten human life or cause risk of bodily injury, such as aerospace, aeronautics, nuclear power, combustion control, transportation, traffic, safety equipment or medical equipment for life support.
4. Design your application so that the product is used within the ranges guaranteed by Hitachi particularly for maximum rating, operating supply voltage range, heat radiation characteristics, installation conditions and other characteristics. Hitachi bears no responsibility for failure or damage when used beyond the guaranteed ranges. Even within the guaranteed ranges, consider normally foreseeable failure rates or failure modes in semiconductor devices and employ systemic measures such as fail-safes, so that the equipment incorporating Hitachi product does not cause bodily injury, fire or other consequential damage due to operation of the Hitachi product.
5. This product is not designed to be radiation resistant.
6. No one is permitted to reproduce or duplicate, in any form, the whole or part of this document without written approval from Hitachi.
7. Contact Hitachi's sales office for any questions regarding this document or Hitachi semiconductor products.

IMPORTANT INFORMATION

READ FIRST

- **READ this user's manual before using this emulator product.**
- **KEEP the user's manual handy for future reference.**

Do not attempt to use the emulator product until you fully understand its mechanism.

Emulator Product:

Throughout this document, the term "emulator product" shall be defined as the following products produced only by Hitachi, Ltd. excluding all subsidiary products.

- E6000 series emulator station
- PC interface board
- User system interface cables
- SIMM memory module
- Optional boards

The user system or a host computer is not included in this definition.

Purpose of the SIMM Memory Module:

This SIMM memory module is installed in the E6000 emulator, and is used in place of the user system memory. This module must only be used for this purpose.

Improvement Policy:

Hitachi, Ltd. (including its subsidiaries, hereafter collectively referred to as Hitachi) pursues a policy of continuing improvement in design, functions, performance, and safety of the emulator product. Hitachi reserves the right to change, wholly or partially, the specifications, design, user's manual, and other documentation at any time without notice.

Target User of the Emulator Product:

This emulator product should only be used by those who have carefully read and thoroughly understood the information and restrictions contained in the user's manual. Do not attempt to use the emulator product until you fully understand its mechanism.

It is highly recommended that first-time users be instructed by users that are well versed in the operation of the emulator product.

LIMITED WARRANTY

Hitachi warrants its emulator products to be manufactured in accordance with published specifications and free from defects in material and/or workmanship. Hitachi, at its option, will repair or replace any emulator products returned intact to the factory, transportation charges prepaid, which Hitachi, upon inspection, determine to be defective in material and/or workmanship. The foregoing shall constitute the sole remedy for any breach of Hitachi's warranty. See the Hitachi warranty booklet for details on the warranty period. This warranty extends only to you, the original Purchaser. It is not transferable to anyone who subsequently purchases the emulator product from you. Hitachi is not liable for any claim made by a third party or made by you for a third party.

DISCLAIMER

HITACHI MAKES NO WARRANTIES, EITHER EXPRESS OR IMPLIED, ORAL OR WRITTEN, EXCEPT AS PROVIDED HEREIN, INCLUDING WITHOUT LIMITATION THEREOF, WARRANTIES AS TO MARKETABILITY, MERCHANTABILITY, FITNESS FOR ANY PARTICULAR PURPOSE OR USE, OR AGAINST INFRINGEMENT OF ANY PATENT. IN NO EVENT SHALL HITACHI BE LIABLE FOR ANY DIRECT, INCIDENTAL OR CONSEQUENTIAL DAMAGES OF ANY NATURE, OR LOSSES OR EXPENSES RESULTING FROM ANY DEFECTIVE EMULATOR PRODUCT, THE USE OF ANY EMULATOR PRODUCT, OR ITS DOCUMENTATION, EVEN IF ADVISED OF THE POSSIBILITY OF SUCH DAMAGES. EXCEPT AS EXPRESSLY STATED OTHERWISE IN THIS WARRANTY, THIS EMULATOR PRODUCT IS SOLD "AS IS ", AND YOU MUST ASSUME ALL RISK FOR THE USE AND RESULTS OBTAINED FROM THE EMULATOR PRODUCT.

State Law:

Some states do not allow the exclusion or limitation of implied warranties or liability for incidental or consequential damages, so the above limitation or exclusion may not apply to you. This warranty gives you specific legal rights, and you may have other rights which may vary from state to state.

The Warranty is Void in the Following Cases:

Hitachi shall have no liability or legal responsibility for any problems caused by misuse, abuse, misapplication, neglect, improper handling, installation, repair or modifications of the emulator product without Hitachi's prior written consent or any problems caused by the user system.

All Rights Reserved:

This user's manual and emulator product are copyrighted and all rights are reserved by Hitachi. No part of this user's manual, all or part, may be reproduced or duplicated in any form, in hard-copy or machine-readable form, by any means available without Hitachi's prior written consent.

Other Important Things to Keep in Mind:

1. Circuitry and other examples described herein are meant merely to indicate the characteristics and performance of Hitachi's semiconductor products. Hitachi assumes no responsibility for any intellectual property claims or other problems that may result from applications based on the examples described herein.
2. No license is granted by implication or otherwise under any patents or other rights of any third party or Hitachi.

Figures:

Some figures in this user's manual may show items different from your actual system.

Limited Anticipation of Danger:

Hitachi cannot anticipate every possible circumstance that might involve a potential hazard. The warnings in this user's manual and on the emulator product are therefore not all inclusive. Therefore, you must use the emulator product safely at your own risk.

SAFETY PAGE

READ FIRST

- **READ** this user's manual before using this emulator product.
- **KEEP** the user's manual handy for future reference.

Do not attempt to use the emulator product until you fully understand its mechanism.

DEFINITION OF SIGNAL WORDS



This is the safety alert symbol. It is used to alert you to potential personal injury hazards. Obey all safety messages that follow this symbol to avoid possible injury or death.



DANGER indicates an imminently hazardous situation which, if not avoided, will result in death or serious injury.



WARNING indicates a potentially hazardous situation which, if not avoided, could result in death or serious injury.



CAUTION indicates a potentially hazardous situation which, if not avoided, may result in minor or moderate injury.



CAUTION used without the safety alert symbol indicates a potentially hazardous situation which, if not avoided, may result in property damage.

NOTE emphasizes essential information.

WARNING

Observe the precautions listed below. Failure to do so will result in a FIRE HAZARD and will damage the user system and the emulator product or will result in PERSONAL INJURY. The USER PROGRAM will be LOST.

- 1. Do not repair or remodel the emulator product by yourself for electric shock prevention and quality assurance.**
- 2. Always switch OFF the E6000 emulator and user system before connecting or disconnecting any CABLES or PARTS.**
- 3. Always switch OFF the E6000 emulator and user system before installing or removing the SIMM memory module.**
- 4. Supply power according to the power specifications and do not apply an incorrect power voltage. Use only the provided power cable.**

Preface

Thank you for purchasing the SIMM memory module (HS6000EMS21H or HS6000EMS22H) for the E6000 emulator. The SIMM memory module can emulate a 2.5-Mbyte or 6.5-Mbyte area by installing it in the SH7010, SH7040, SH7050 series E6000 emulator (HS7010EPI60H, HS7040EPI60H or SH7050EPI60H).

Contents

Section 1 Components	1
Section 2 SIMM Memory Module Outline	2
2.1 SIMM Memory Module Functions.....	2
2.2 Access Restrictions.....	3
Section 3 SIMM Memory Module	7
Section 4 Installation	12

Section 1 Components

Figure 1 shows the SIMM memory module, and table 1 lists its components.

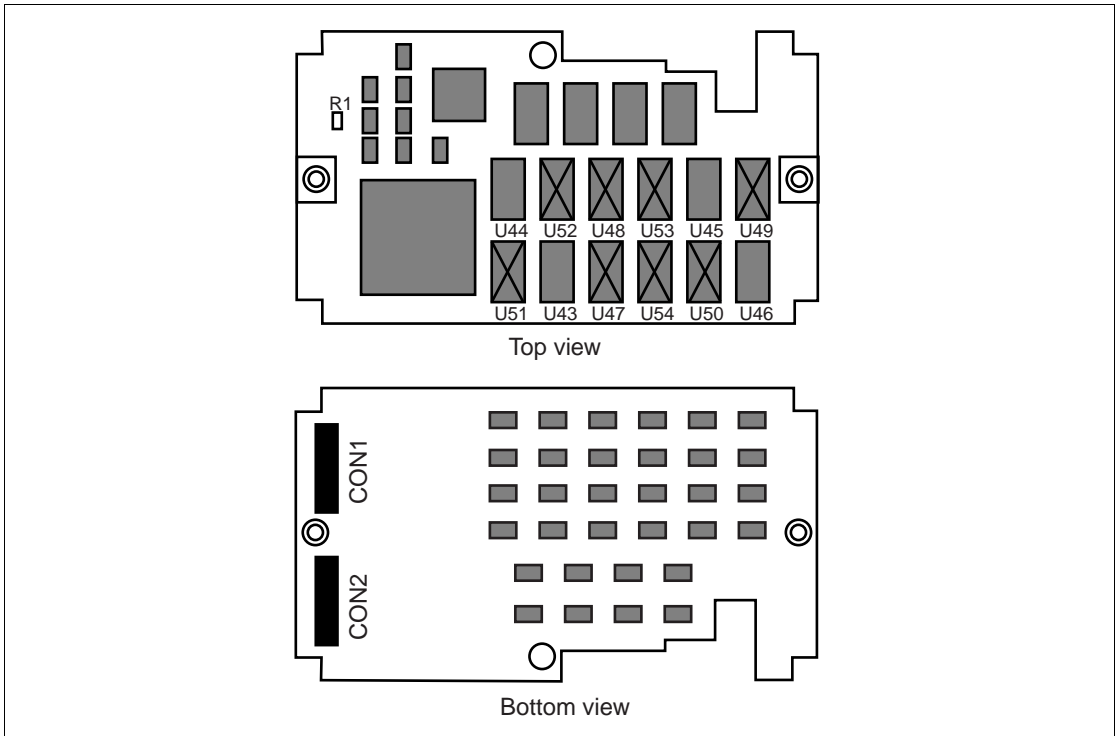


Figure 1 E6000 SIMM Memory Module for the SH7010, SH7040, SH7050

Table 1 Components

Item	Quantity	Remarks
SIMM memory module	1	In HS6000EMS21H, R1 and U47 to U54 cannot be used.
Screw (M2.6 x 6 mm)	2	For fastening cable head (with flat washer)
User's Manual for HS6000EMS21H/HS6000EMS22H	1	This manual

Section 2 SIMM Memory Module Outline

2.1 SIMM Memory Module Functions

Tables 2 and 3 and list the SIMM memory module functions.

Table 2 SIMM Memory Module Functions of HS6000EMS21H

Item	Specifications
Memory size	<ul style="list-style-type: none">• 2.5 Mbytes (128 kbytes × 4 areas and 512 kbytes × 4 areas)
Operating frequency	<ul style="list-style-type: none">• 128 kbytes × 4 areas 4 MHz ≤ ϕ (operating frequency) ≤ 33 MHz: 2-cycle access• 512 kbytes × 4 areas 4 MHz ≤ ϕ (operating frequency) ≤ 20 MHz: 3-cycle access 20 MHz < ϕ (operating frequency) ≤ 33 MHz: 4-cycle access
Access restrictions (E.g.: Read-only or guarded (no access))	<ul style="list-style-type: none">• Access restrictions can be specified in 128-kbyte, 1-Mbyte, 2-Mbyte, and 4-Mbyte units (see figures 2 and 3).• Specifies access restriction for the emulation memory.
Bus width	<ul style="list-style-type: none">• 8 bits/16 bits/32 bits (Depends on the MCU used.)

Table 3 SIMM Memory Module Functions of HS6000EMS22H

Item	Specifications
Memory size	<ul style="list-style-type: none"> 6.5 Mbytes (128 kbytes × 4 areas and 512 kbytes × 12 areas)
Operating frequency	<ul style="list-style-type: none"> 128 kbytes × 4 areas 4 MHz ≤ φ (operating frequency) ≤ 33 MHz: 2-cycle access 512 kbytes × 12 areas 4 MHz ≤ φ (operating frequency) ≤ 20 MHz: 3-cycle access 20 MHz < φ (operating frequency) ≤ 33 MHz: 4-cycle access
Number of cycles	<ul style="list-style-type: none"> 2-cycle access: 128 kbytes × 4 areas at operation frequency of 33 MHz 4-cycle access: 512 kbytes × 12 areas at operation frequency of 33 MHz
Access restrictions (E.g.: Read-only or guarded (no access))	<ul style="list-style-type: none"> Access restrictions can be specified in 128-kbyte, 1-Mbyte, 2-Mbyte, and 4-Mbyte units (see figures 2 and 3). Specifies access restriction for the emulation memory.
Bus width	<ul style="list-style-type: none"> 8 bits/16 bits/32 bits (Depends on the MCU used.)

Notes: 1 When specifying the CS3 area for the emulation memory in the SIMM memory module, set bus control register 1 (BCR1) in the bus state controller so that the CS3 area becomes the usual emulation memory for the emulator. The SH7011 has no BCR1.

2 When using the SIMM memory module, set the wait state control register (WCR) according to the device frequency.
E.g.: When accessing a 512 x 4 byte area at 28.7 MHz, set the WCR so that the area is accessed in 4 cycles.

2.2 Access Restrictions

Access Restrictions for emulation memory within the SIMM memory module can be specified in 128-kbyte or 512-kbyte units. However, to avoid competition for access between the emulation memory and user memory, the MCU inhibits the output of strobe signals (/WRHH, /WRHL, /WRH, /WRL, /CASHH, /CASHL, /CAH, /CASL, /CS0 to /CS3, and RD/_WR) to the user system in units of the memory blocks shown in figures 2 and 3, instead of using the boundaries of the emulation memory.

For example, when the address range H'000C0000 to H'000DFFFF (SB6) is specified as the emulation memory, and that address range is accessed, the strobe signals listed above will not be output to the user system.

Note: Even if less memory than the size of the memory block is specified for use as emulation memory, the MCU inhibits the output of strobe signals by memory block unit. For example,

when a 128-kbyte emulation memory requires restriction of access to the address range H'00C00000 to H'00DFFFFF (LB10), the access restriction is applied to LB10 (2 Mbytes), and output of the strobe signals is inhibited.

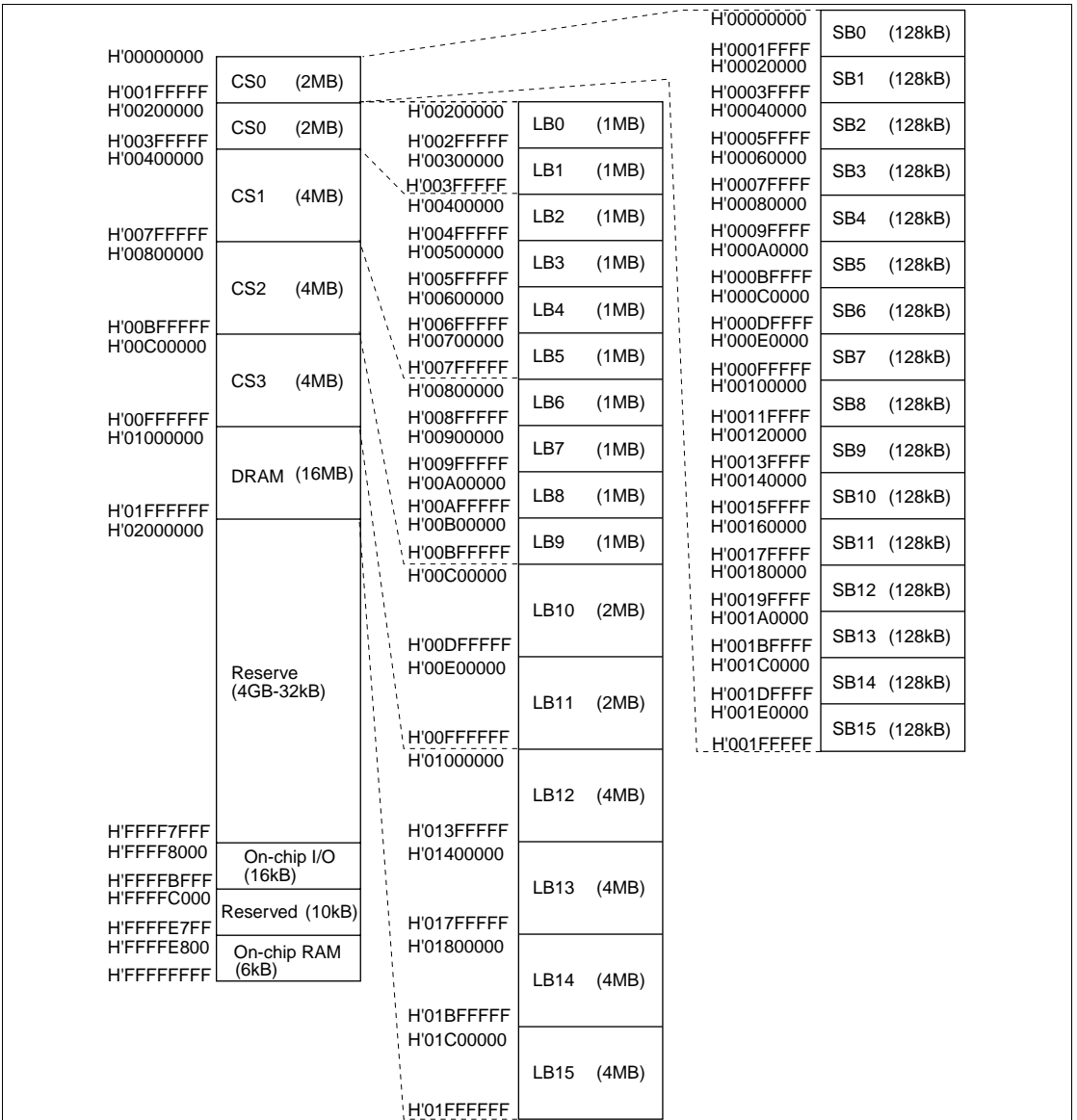


Figure 2 Memory Blocks in Extended Mode without ROM

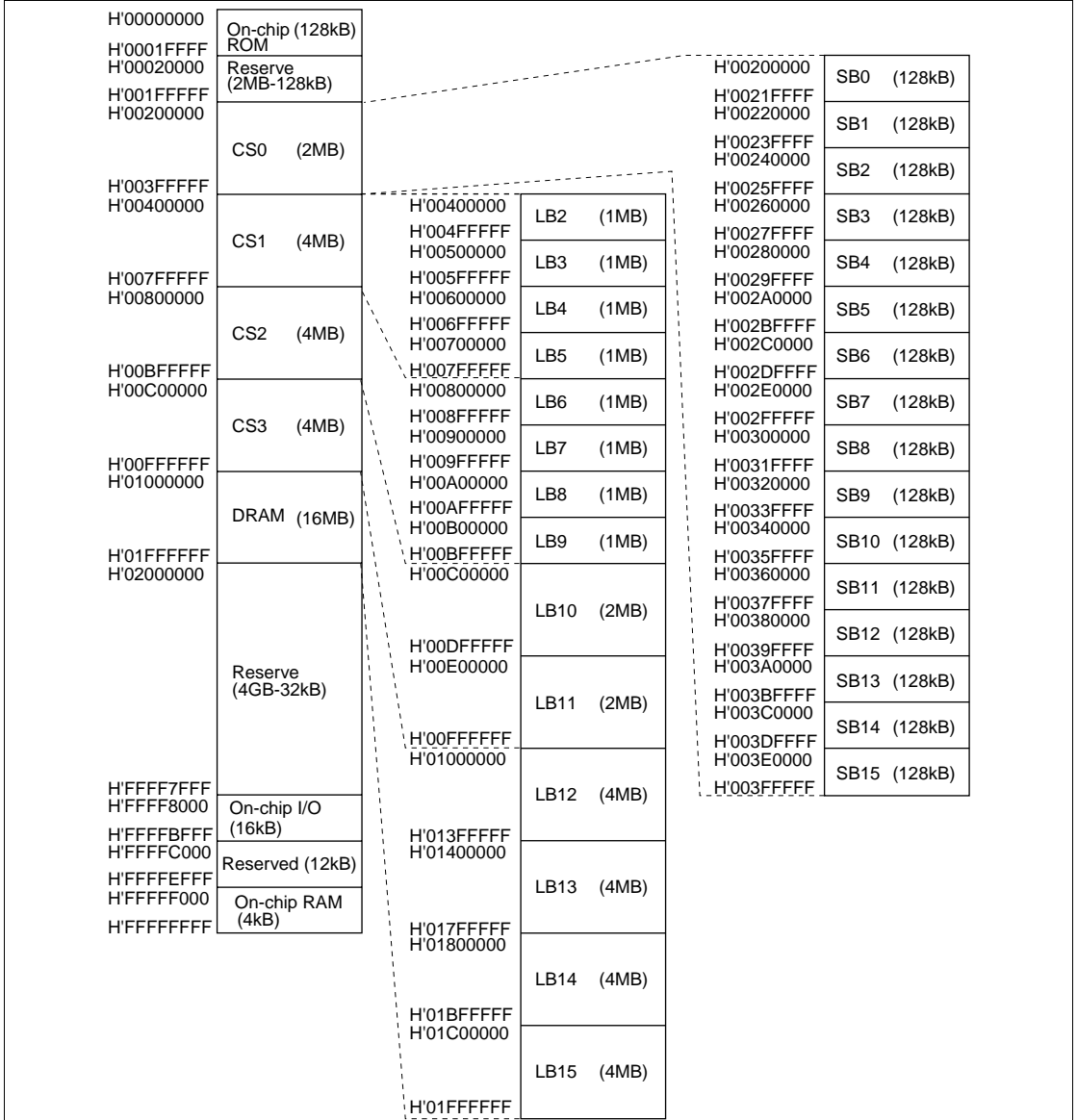


Figure 3 Memory Blocks in Extended Mode with ROM

Note: The memory map of internal ROM, internal RAM, internal I/O, and reserved area will differ according to the target MCU. For details, refer to the relevant hardware manual.

Section 3 SIMM Memory Module

The HS6000EMS21H SIMM memory module has 4 areas of 128-kbyte and 512-kbyte units. The HS6000EMS22H SIMM memory module has 4 areas of 128-kbyte units and 12 areas of 512-kbyte units. Each area can be allocated to a 128-kbyte or 512-kbyte boundary address space, and one area can have a continuous 128-kbyte or 512-kbyte memory. Figure 4 shows an example of address allocation.

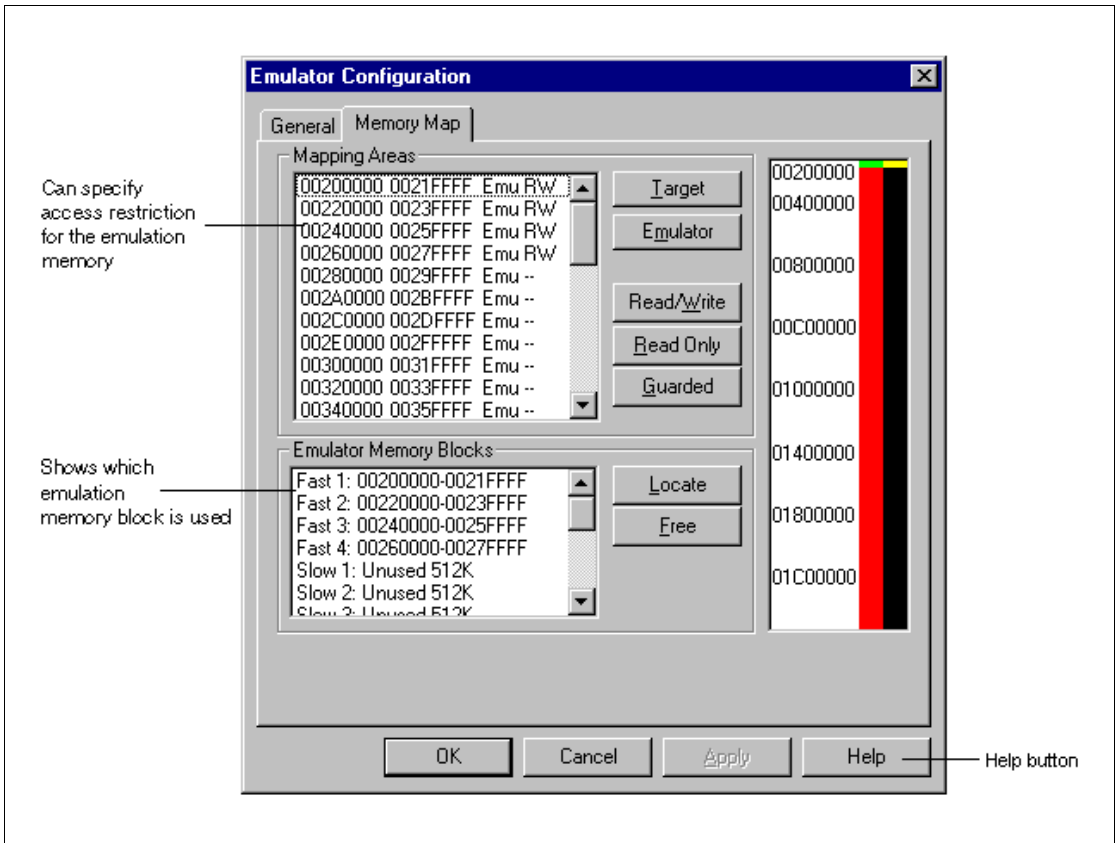


Figure 4 Memory Map Dialog Box

In the HDI Setup menu, open the Configure Platform dialog box, and allocate emulation memory (Emulator Read-write or Emulator Read-only) to the designated address space through the Memory Map dialog box. In this tag, Emulator Guarded memory can also be set.

The following dialog boxes show how to allocate emulation memory to memory range H'00400000-H'004FFFFF. In this example, a R/W memory is selected for the emulation memory.

1. Select memory range 00400000-004FFFFF from the Mapping Area list box.
2. Click the Emulator button.

3. Click the Read/Write button.

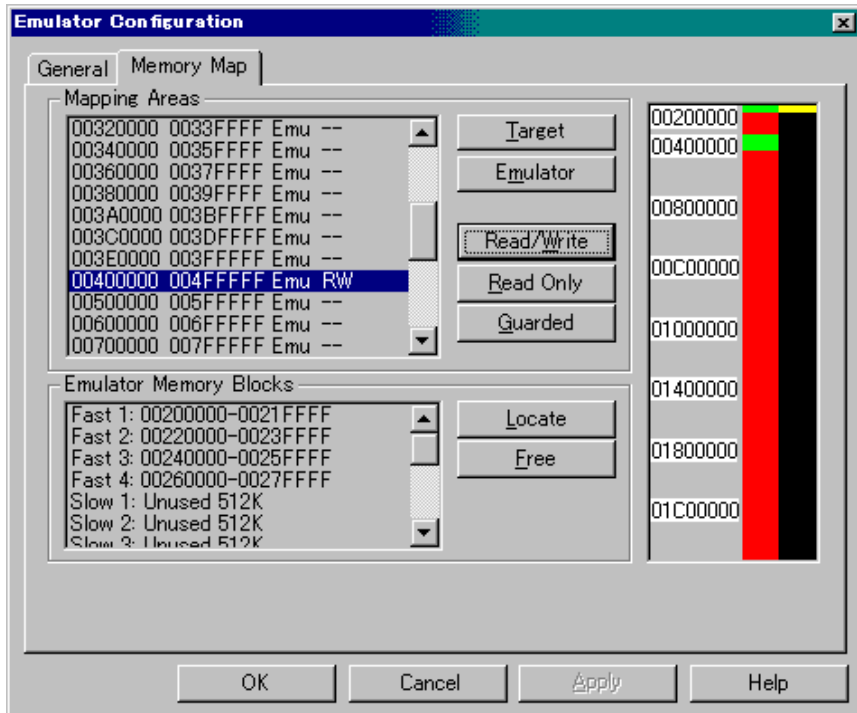


Figure 5 Memory Allocation 1

- Select an area of unused memory from the Emulator Memory Blocks list box.
In this example, Slow 1 and Slow 2 are selected. Then click the Locate button.

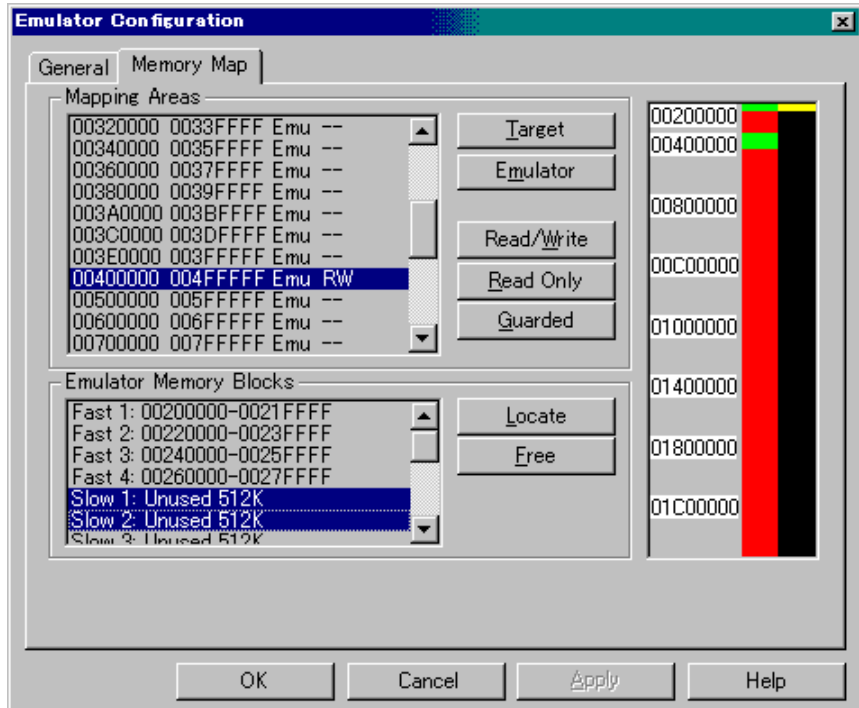


Figure 6 Memory Allocation 2

5. The Locate Emulator Memory Blocks dialog box displays an available base address. Click OK.

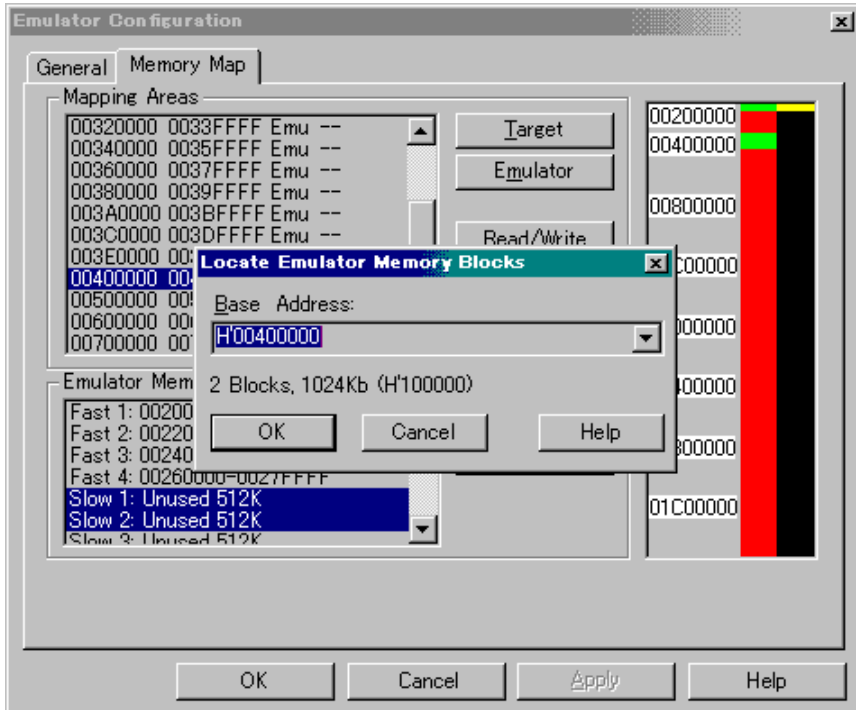


Figure 7 Memory Allocation 3

6. Emulation memory has been set successfully.

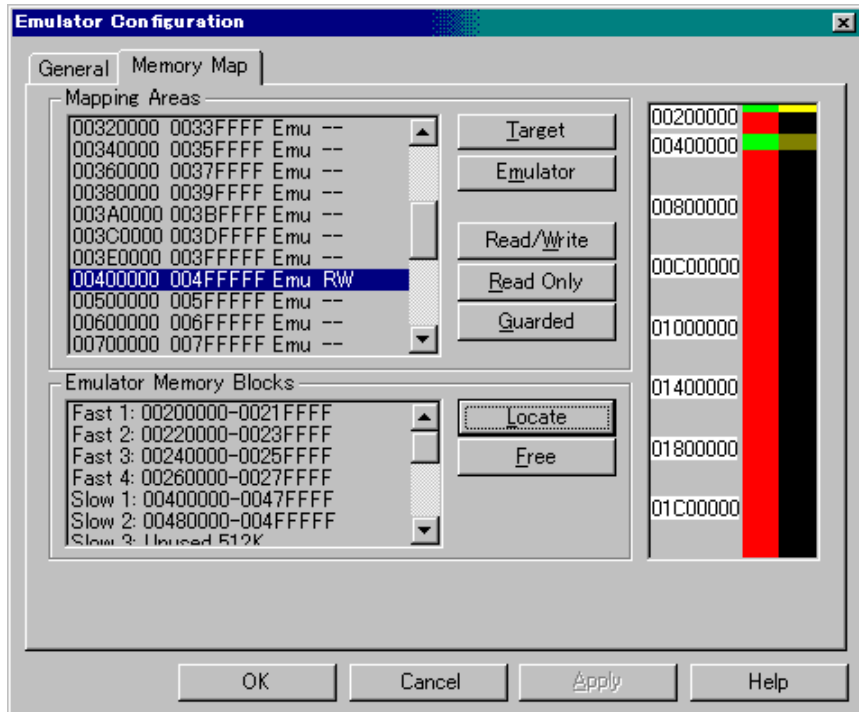


Figure 8 Memory Allocation 4

For details, refer to the HDI online help.

Section 4 Installation

Be sure to switch off the emulator and user system before installation.

WARNING

1. Always switch OFF the emulator product and user system, before connecting or disconnecting the SIMM memory module.

Failure to do so will result in a FIRE HAZARD and will damage the user system and emulator product or will result in PERSONAL INJURY.

2. Before closing the cover of the emulator, be sure to check that no foreign objects such as metal fractions are left inside the emulator station.

Failure to do so will result in a FIRE HAZARD and will damage the user system and emulator product or will result in PERSONAL INJURY.

To install the SIMM memory module in the E6000 emulator station,

1. Remove the four screws from the sides of the emulator station.
2. Pull the emulator cover upward and remove it.
3. Insert the CON1 and CON2 connectors of the SIMM memory module into the CON8 and CON9 connectors in the E6000 emulator station.
4. Fasten the SIMM memory module to the E6000 emulator by attaching the SIMM memory board to the spacer and then a screw and a washer.
5. Close the emulator cover and fasten it with the four screws.
6. Connect the emulator station to the host computer and turn on the E6000 emulator station.
7. Start the HDI. Open the Configure Platform dialog box from the Setup menu and check that the emulation memory can be displayed and selected through the Memory Map dialog box.

Note: The HS7040EPI60H has a cooling fan. Do not pull or apply excessive strength to the cable of the evaluation chip cooling fan.

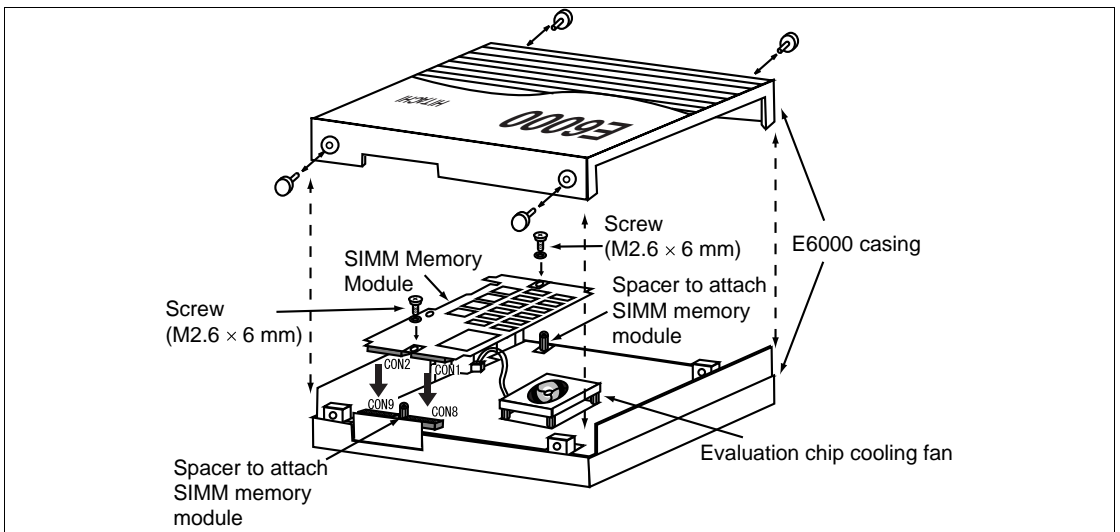


Figure 9 Installing SIMM Memory Module

To remove the SIMM memory module from the E6000 emulator station,

1. Remove the four screws from the sides of the emulator station.
2. Pull the emulator cover upward and remove it.
3. Remove the screw for fastening the SIMM memory module.
4. Remove the CON1 and CON2 connectors of the SIMM memory module from the CON8 and CON9 connectors.
5. Close the emulator cover and fasten it with the four screws.

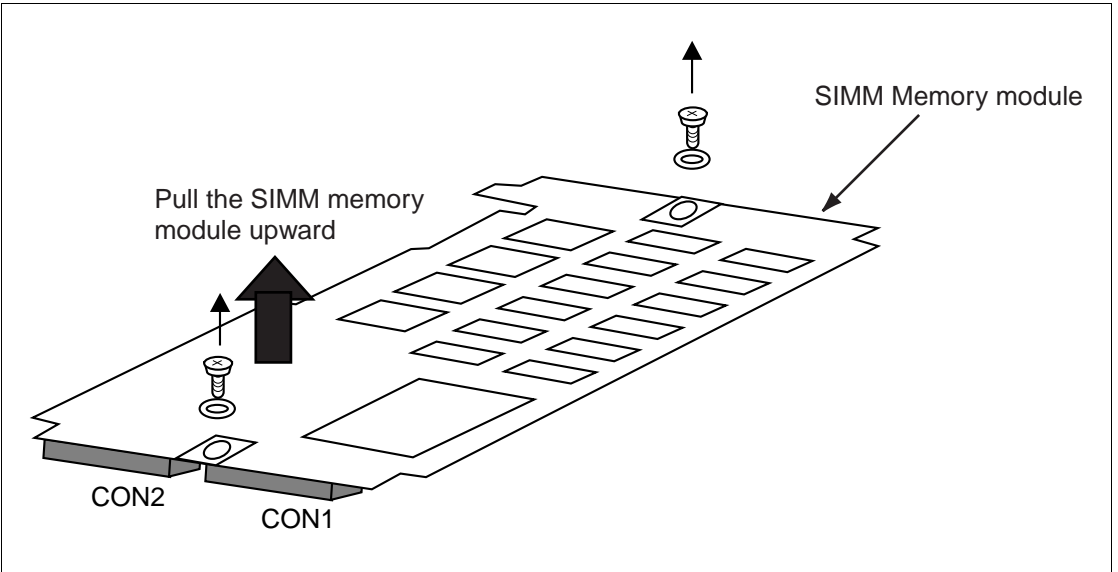


Figure 10 Removing SIMM Memory Module